

# MOS FIELD EFFECT TRANSISTOR 2SK2983

# SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

#### **DESCRIPTION**

This product is N-Channel MOS Field Effect Transistor designed for high current switching application.

#### **FEATURES**

· Low on-resistance

RDS(on)1 = 20 m $\Omega$  (MAX.) (VGS = 10 V, ID = 15 A)

 $R_{DS(on)2} = 27 \text{ m}\Omega \text{ (MAX.)} \text{ (Vgs} = 4.5 \text{ V, Ip} = 15 \text{ A)}$ 

- Low Ciss Ciss = 1200 pF TYP.
- · Built-in gate protection diode

# **ORDERING INFOMATION**

| PART NUMBER | PACKAGE  |
|-------------|----------|
| 2SK2983     | TO-220AB |
| 2SK2983-S   | TO-262   |
| 2SK2983-ZJ  | TO-263   |

# ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

| Drain to Source Voltage Note1       | VDSS               | 30          | V  |
|-------------------------------------|--------------------|-------------|----|
| Gate to Source Voltage Note2        | Vgss               | ±20         | V  |
| Drain Current (DC)                  | I <sub>D(DC)</sub> | ±30         | Α  |
| Drain Current (pulse) Note3         | D(pulse)           | ±120        | Α  |
| Total Power Dissipation (TA = 25°C) | PT                 | 1.5         | W  |
| Total Power Dissipation (Tc = 25°C) | PT                 | 50          | W  |
| Channel Temperature                 | Tch                | 150         | °C |
| Storage Temperature                 | Tstg               | -55 to +150 | °C |

Notes1. Vgs = 0 V

2. Vps = 0 V

**3.** PW  $\leq$  10  $\mu$  s, Duty Cycle  $\leq$  1 %

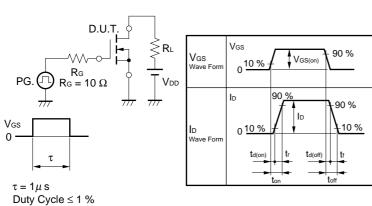
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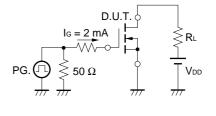
# **ELECTRICAL CHARACTERISTICS (TA = 25 °C)**

| CHARACTERISTICS                     | SYMBOL               | TEST CONDITIONS   | MIN. | TYP. | MAX. | UNIT |
|-------------------------------------|----------------------|---|------|------|------|------|
| Drain to Source On-state Resistance | RDS(on)1             | Vgs = 10 V, Ip = 15 A   |      | 13.0 | 20.0 | mΩ   |
|                                     | RDS(on)2             | V <sub>G</sub> S = 4.5 V, I <sub>D</sub> = 15 A                           |      | 18.0 | 27.0 | mΩ   |
| Gate to Source Cut-off Voltage      | VGS(off)             | Vps = 10 V, Ip = 1 mA   | 1.0  | 1.5  | 2.0  | V    |
| Forward Transfer Admittance         | yfs                  | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 15 A                             | 9.0  | 19   |      | S    |
| Drain Leakage Current               | Inss                 | Vps = 30 V, Vgs = 0 V   |      |      | 10   | μΑ   |
| Gate to Source Leakage Current      | Igss                 | Vgs = ±20 V, Vps = 0 V  |      |      | ±10  | μΑ   |
| Input Capacitance                   | Ciss                 | V <sub>DS</sub> = 10 V  |      | 1200 |      | pF   |
| Output Capacitance                  | Coss                 | V <sub>G</sub> S = 0 V  |      | 530  |      | pF   |
| Reverse Transfer Capacitance        | Crss                 | f = 1 MHz   |      | 250  |      | pF   |
| Turn-on Delay Time                  | td(on)               | ID = 15 A   |      | 50   |      | ns   |
| Rise Time                           | tr                   | $V_{GS(on)} = 10 \text{ V}$ $V_{DD} = 15 \text{ V}$ $R_G = 10 \Omega$     |      | 820  |      | ns   |
| Turn-off Delay Time                 | td(off)              |   |      | 100  |      | ns   |
| Fall Time                           | tf                   |   |      | 170  |      | ns   |
| Total Gate Charge                   | Q <sub>G</sub>       | I <sub>D</sub> = 30 A<br>V <sub>DD</sub> = 24 V<br>V <sub>GS</sub> = 10 V |      | 30   |      | nC   |
| Gate to Source Charge               | Qgs                  |   |      | 4.5  |      | nC   |
| Gate to Drain Charge                | Q <sub>GD</sub>      |   |      | 7.5  |      | nC   |
| Body Diode Forward Voltage          | V <sub>F</sub> (S-D) | IF = 30 A, VGS = 0 V  |      | 0.8  |      | V    |
| Reverse Recovery Time               | trr                  | IF = 30 A, VGS = 0 V  |      | 35   |      | ns   |
| Reverse Recovery Charge             | Qrr                  | $di/dt = 100 \text{ A} / \mu \text{S}$                                    |      | 65   |      | nC   |

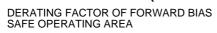
# **TEST CIRCUIT 1 SWITCHING TIME**

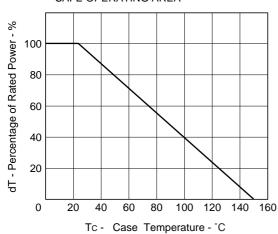


# **TEST CIRCUIT 2 GATE CHARGE**

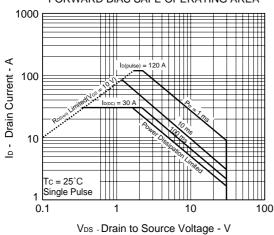


# TYPICAL CHARACTERISTICS (TA = 25 °C)

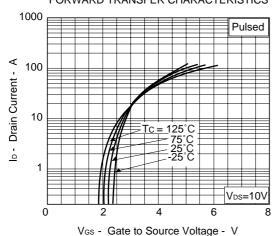




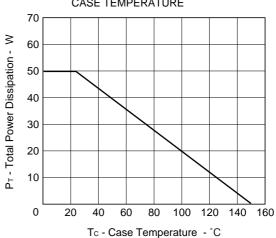
#### FORWARD BIAS SAFE OPERATING AREA



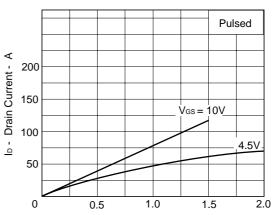
# FORWARD TRANSFER CHARACTERISTICS



# TOTAL POWER DISSIPATION vs. CASE TEMPERATURE

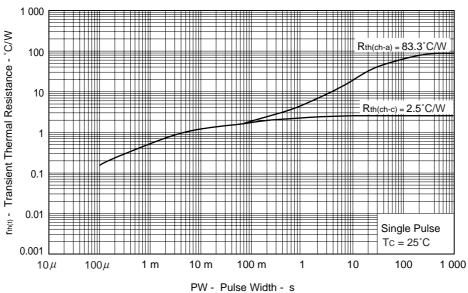


#### DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

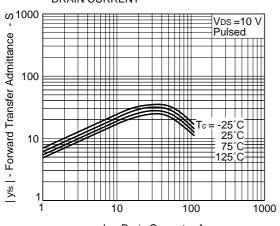


V<sub>DS</sub> - Drain to Source Voltage - V

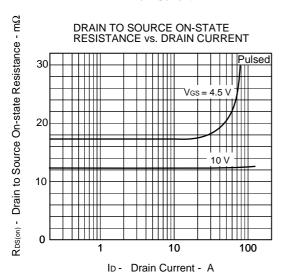
#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



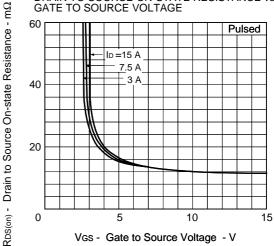
# FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



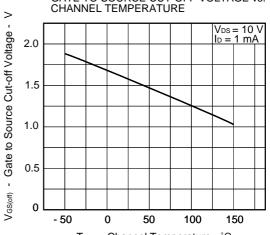
ID- Drain Current - A



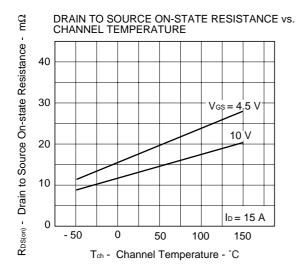
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

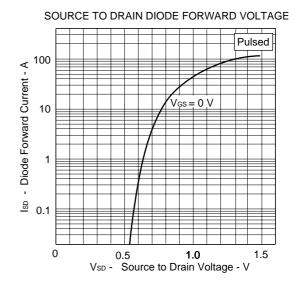


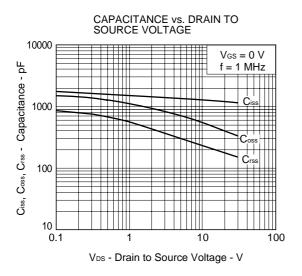
GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE

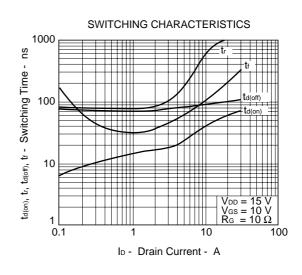


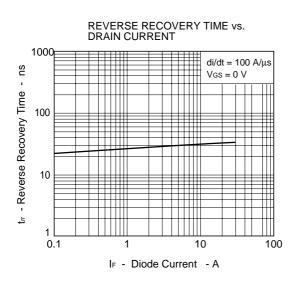
Tch - Channel Temperature - °C

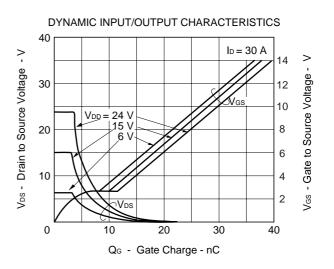








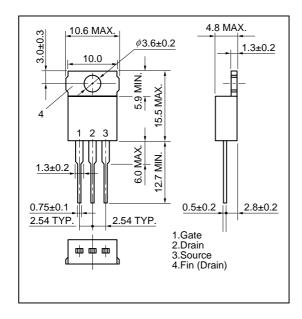




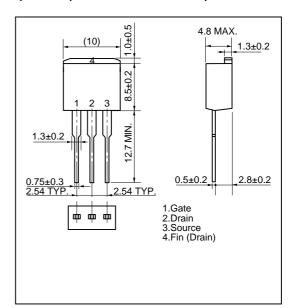


# **PACKAGE DRAWINGS (Unit:mm)**

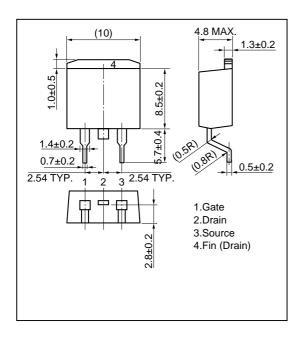
# 1)TO-220AB (MP-25)



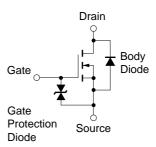
# 2)TO-262 (TO-220 Fin Cut:MP-25S)



# 3)TO-263 (JEDEC TYPE:MP-25ZJ)



#### **EQUIVALENT CIRCUIT**



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD.

When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device

2SK2983



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Anti-radioactive design is not implemented in this product.

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